

## **Data sheet**

Micro-acoustic diplexer GPS L5 + GNSS L1

Part number: B1267

Ordering code: B39162B1267L210

Date: May 29, 2020

Version: 2.0

DCN: 80-PA243-479 Rev. A

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### 1 Application

- Diplexer for GPS L5 and GNSS L1 navigation bands with single ended 50Ω ports.
- Ultra-low-loss acoustic structure.
- Highly integrated with no external matching.
- Usable GNSS L1 pass bands: 1559.05 1563.15 MHz (BeiDou), 1574.39 1576.45 MHz (GPS), 1597.55 1605.89 MHz (Glonass). Usable GPS L5 pass band: 1166.22 1186.68 MHz.

### 2 Features

- Package height 0.6 mm
- Package size 1.5 mm × 1.1 mm
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

### 3 Package

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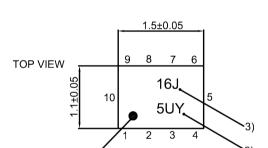
# BOTTOM VIEW (0.075)

0.585

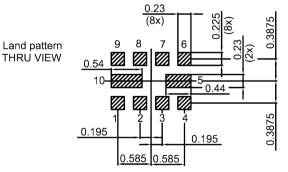
Pad and pitch tolerance ±0.05

SIDE VIEW





- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number



Landing pad tolerance -0.02

**Figure 1:** Drawing of package with package height A = 0.7 mm (max.). See Sec. Package information (p. 22).

### 4 Pin configuration

■ 1 ANT

■ 6 GPS L5

■ 9 GNSS L1

■ 2, 3, 4, 5, Ground 7, 8, 10



### 5 Matching circuit

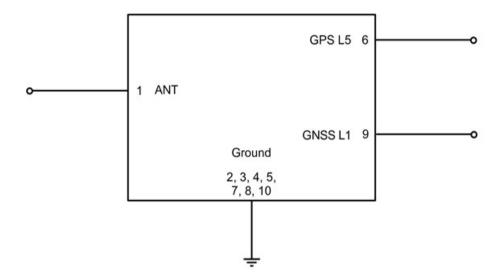


Figure 2: Schematic of matching circuit. No external matching components required.



### 6 Characteristics ANT - GPS L5

Temperature range for specification ANT terminating impedance GNSS L1 terminating impedance GPS L5 terminating impedance  $T_{\text{SPEC}}$  = -30 °C ... +85 °C  $Z_{\text{ANT}}$  = 50  $\Omega$ 

 $Z_{ANT} = 50 \Omega$   $Z_{GNSS L1} = 50 \Omega$  $Z_{GPS L5} = 50 \Omega$ 

Characteristics ANT – GPS L5			$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	<b>typ.</b> @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{\tiny SPEC}} \end{array}$	
Insertion loss		O				
	1166.22 1186.68	MHz	_	1.2	1.5 <sup>1)</sup>	dB
	1166.22 1186.68	MHz	_	1.2	2.2	dB
VSWR						
@ ANT port	1166.22 1186.68	MHz	_	1.4	1.8 <sup>1)</sup>	
	1166.22 1186.68	MHz	_	1.4	2.3	
@ GPS L5 port	1166.22 1186.68	MHz	_	1.4	1.8 <sup>1)</sup>	
	1166.22 1186.68	MHz	_	1.4	2.3	
Amplitude ripple (p-p)		Δα				
	1166.22 1186.68	MHz	_	0.4	1.5 <sup>1)</sup>	dB
	1166.22 1186.68	MHz	_	0.4	2.0	dB
Attenuation		a				
	100 824	MHz	35	45	_	dB
	824 915	MHz	35	45	_	dB
	825 960	MHz	35	45	_	dB
	1427 1463	MHz	322)	442)	_	dB
	1559 1606	MHz	20	40	_	dB
	1710 1785	MHz	35 <sup>2)</sup>	432)	_	dB
	1850 2025	MHz	35 <sup>2)</sup>	432)	_	dB
	2300 2690	MHz	302)	482)	_	dB
	3400 3800	MHz	25 <sup>2)</sup>	492)	_	dB
	4400 4900	MHz	24	34	_	dB
	5150 5925	MHz	23	33	_	dB

Valid for typical temperature  $T = +25 \,^{\circ}\text{C}$ .

<sup>&</sup>lt;sup>2)</sup> Averaged over any 10 MHz.



### 7 Characteristics ANT - GNSS L1

Temperature range for specification  $T_{\text{SPEC}} = -30 \,^{\circ}\text{C} \dots +85 \,^{\circ}\text{C}$ 

ANT terminating impedance  $Z_{\rm ANT} = 50~\Omega$  GNSS L1 terminating impedance  $Z_{\rm GNSS\,L1} = 50~\Omega$  GPS L5 terminating impedance  $Z_{\rm GPS\,L5} = 50~\Omega$ 

Characteristics ANT – GNSS L1	$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	<b>typ.</b> @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{\tiny SPEC}} \end{array}$			
Insertion loss		α				
ANT – BeiDou B1	1559.05 1563.15	MHz	_	1.5 <sup>3)</sup>	1.91),3)	dB
	1559.05 1563.15	MHz	_	1.5 <sup>3)</sup>	2.33)	dB
ANT – GPS L1	1574.39 1576.45	MHz	_	1.2	1.5 <sup>1)</sup>	dB
	1574.39 1576.45	MHz	_	1.2	1.8	dB
ANT – GLONASS L1	1597.55 1605.89	MHz	_	1.64)	2.01),4)	dB
	1597.55 1605.89	MHz	_	1.64)	2.42,4)	dB
Group delay ripple (p-p)		Dt				
ANT – GLONASS L1	1597.55 1605.89	MHz	_	3	15	ns
VSWR						
@ ANT port	1559.05 1563.15	MHz	_	1.5	1.8 <sup>1)</sup>	
	1559.05 1563.15	MHz	_	1.5	2.3	
	1574.39 1576.45	MHz	_	1.3	1.6 <sup>1)</sup>	
	1574.39 1576.45	MHz	_	1.3	2.0	
	1597.55 1605.89	MHz	_	1.5	1.71)	
	1597.55 1605.89	MHz	_	1.5	2.0	
@ GNSS L1 port	1559.05 1563.15	MHz	_	1.5	1.8 <sup>1)</sup>	
	1559.05 1563.15	MHz	_	1.5	2.3	
	1574.39 1576.45	MHz	_	1.3	1.6 <sup>1)</sup>	
	1574.39 1576.45	MHz	_	1.3	2.0	
	1597.55 1605.89	MHz	_	1.5	1.71)	
	1597.55 1605.89	MHz	_	1.5	2.0	
Amplitude ripple (p-p)		Δα				
ANT – BeiDou B1	1559.05 1563.15	MHz	_	0.1	1.3 <sup>1)</sup>	dB
	1559.05 1563.15	MHz	_	0.1	1.8	dB
ANT – GPS L1	1574.39 1576.45	MHz	_	0.1	1.3 <sup>1)</sup>	dB
	1574.39 1576.45	MHz	_	0.1	1.8	dB
ANT – GLONASS L1	1597.55 1605.89	MHz	_	0.3	1.3 <sup>1)</sup>	dB
	1597.55 1605.89	MHz	_	0.3	1.8	dB
Attenuation		α				
	100 824	MHz	35	45	_	dB
	824 915	MHz	35	44	_	dB
	825 960	MHz	35	44	_	dB
	1166 1187	MHz	25	43	_	dB
	1427 1463	MHz	32	40	_	dB



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Characteristics ANT – GNSS L1			in. T <sub>SPEC</sub>	<b>typ.</b> @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
1710 1785	MHz	3	35	44	_	dB
1850 2025	MHz	3	<b>7</b> <sup>5)</sup>	45 <sup>5)</sup>	_	dB
2300 2690	MHz	3	32	45	_	dB
3400 3800	MHz	2	25	40	_	dB
4400 4900	MHz	2	25	37	_	dB
5150 5925	MHz	2	25	40	_	dB

Valid for typical temperature T = +25 °C. Valid for temperature T = -30 °C...+60 °C. 2)

Averaged over any 4.092 MHz.

<sup>4)</sup> Averaged over any 1.022 MHz.

Averaged over any 10 MHz.



### 8 **Maximum ratings**

Storage temperature	$T_{\rm STG}^{2)} = -40 ^{\circ}{\rm C} \dots +85 ^{\circ}{\rm C}^{1)}$	
DC voltage	$ V_{DC}  = 5.0 \text{ V (max.)}^{3)}$	
ESD voltage		
	$V_{ESD}^{4)} = 225 \text{ V (max.)}$	Machine model.
	$V_{\rm ESD}^{5)} = 400  \rm V  (max.)$	Human body model.
	$V_{\rm ESD}^{6)} = 700  \rm V  (max.)$	Charged device model.
Input power	P <sub>IN</sub>	
@ ANT port: 1166.22 1186.68 MHz	10 dBm	Continuous wave for 3000 h @ 50 °C.
@ ANT port: 1559.05 1605.89 MHz	10 dBm	Continuous wave for 3000 h @ 50 °C.

Extended upper limit: 96h@125°C acc. to IEC 60068-2-2-Bb.

Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C. 2)

<sup>168</sup>h Damp Heat Steady State acc. to IEC 60068-2-67 Cy.

<sup>4)</sup> According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

<sup>5)</sup> According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.

According to JESD22-C101C (CDM – Field Induced Charged Device Model), 3 negative & 3 positive pulses.



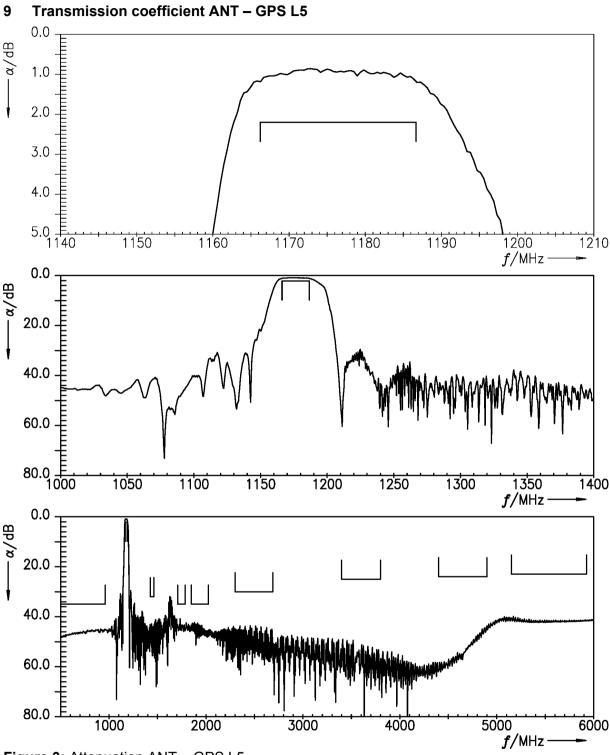
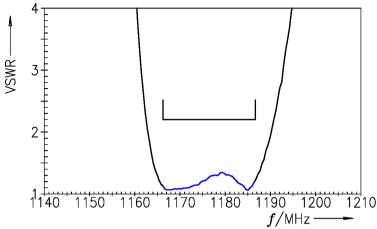


Figure 3: Attenuation ANT - GPS L5.



### 10 Reflection coefficients ANT - GPS L5



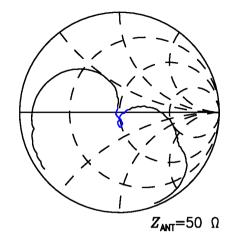
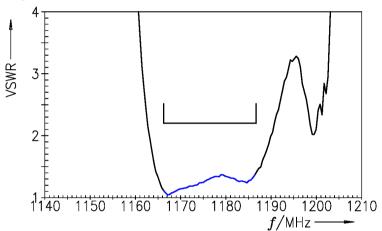


Figure 4: Reflection coefficient at ANT port.



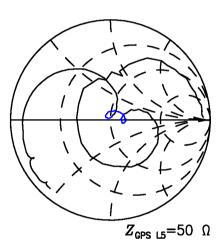


Figure 5: Reflection coefficient at GPS L5 port.



### 11 Transmission coefficient ANT - GNSS L1

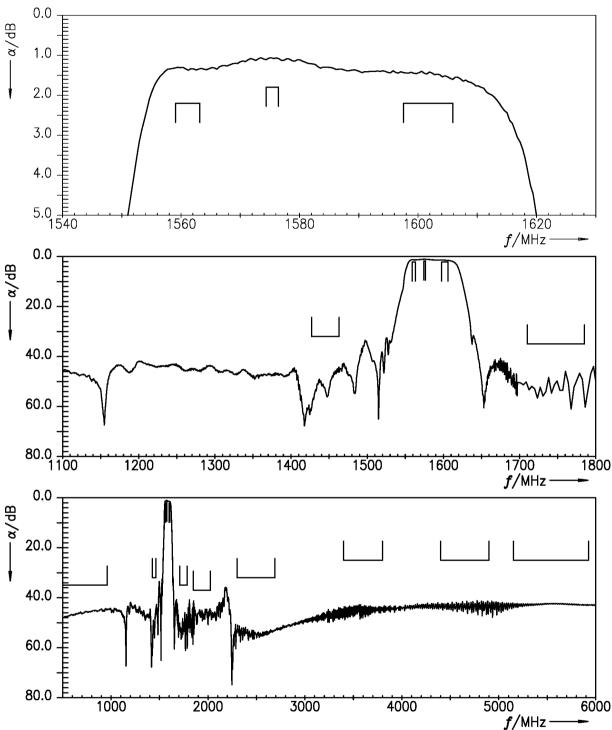
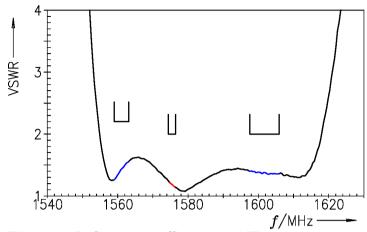


Figure 6: Attenuation ANT - GNSS L1.

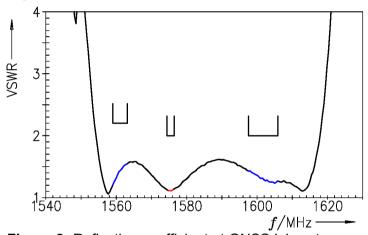


### 12 Reflection coefficients ANT - GNSS L1



 $Z_{ANT}=50 \Omega$ 

Figure 7: Reflection coefficient at ANT port.



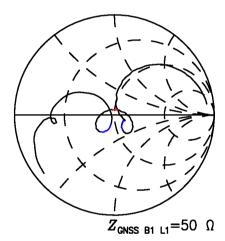


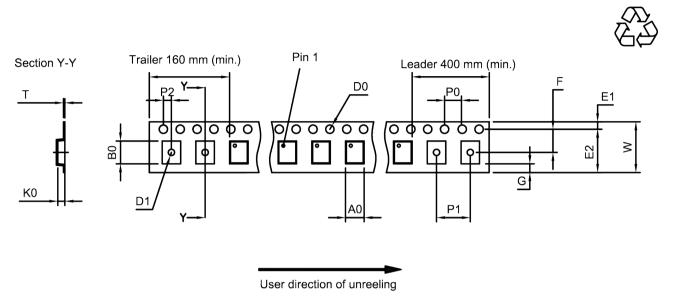
Figure 8: Reflection coefficient at GNSS L1 port.



### 13 Packing material

### 13.1 Tape

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**Figure 9:** Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

<b>A</b> <sub>0</sub>	1.35±0.05 mm	E <sub>2</sub>	6.25 mm (min.)		P <sub>1</sub>	4.0±0.1 mm
B <sub>0</sub>	1.75±0.05 mm	 F	3.5±0.05 mm		$P_2$	2.0±0.05 mm
$D_0$	1.5+0.1/-0 mm	G	0.75 mm (min.)		Т	0.25±0.03 mm
D <sub>1</sub>	0.8 mm (min.)	$\mathbf{K}_0$	0.76±0.05 mm	_	W	8.0+0.3/-0.1 mm
E <sub>1</sub>	1.75±0.1 mm	P <sub>0</sub>	4.0 <sub>±0.1</sub> mm	_		

Table 1: Tape dimensions.

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### 13.2 Reel with diameter of 180 mm

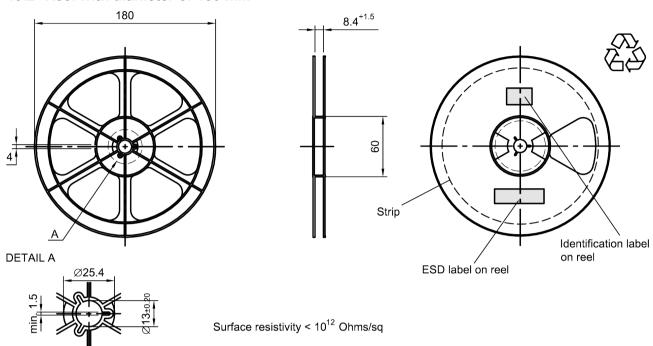


Figure 10: Drawing of reel (first-angle projection) with diameter of 180 mm.

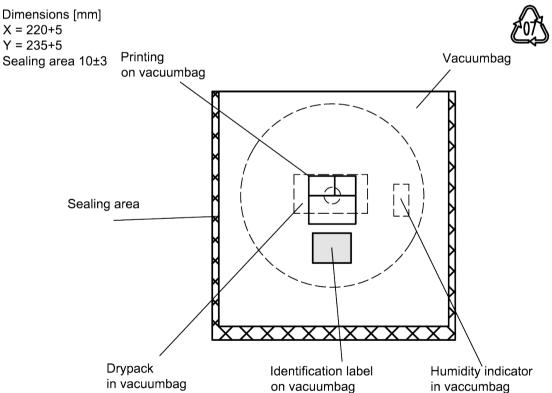


Figure 11: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

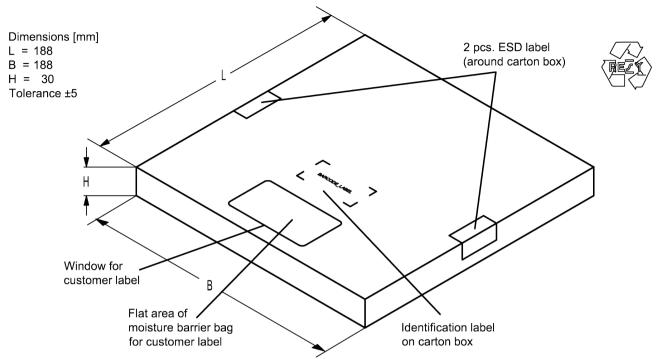
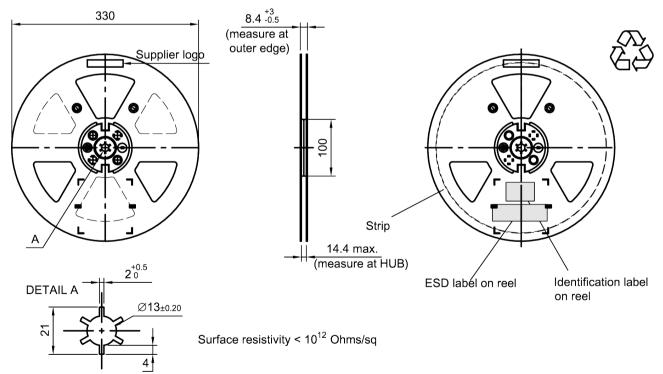


Figure 12: Drawing of folding box for reel with diameter of 180 mm.

### 13.3 Reel with diameter of 330 mm



**Figure 13:** Drawing of reel (first-angle projection) with diameter of 330 mm.



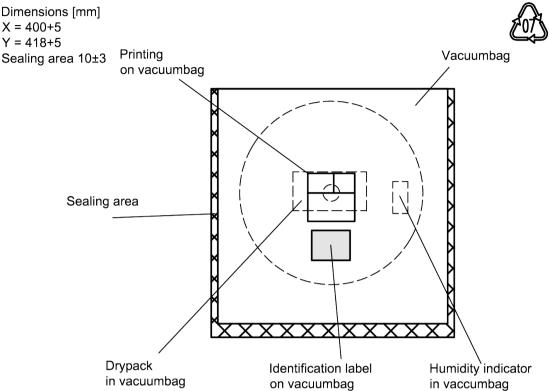


Figure 14: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

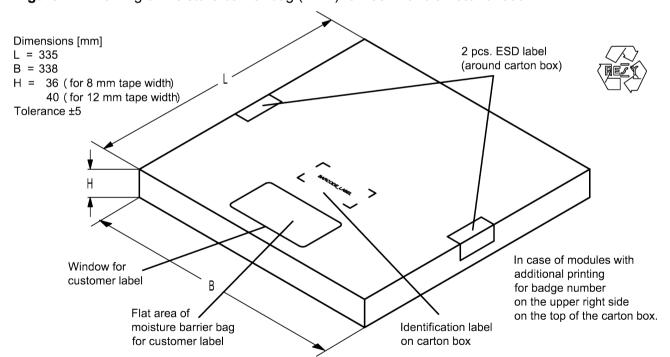


Figure 15: Drawing of folding box for reel with diameter of 330 mm.



### 14 Marking

Products are marked with product type number and lot number encoded according to Table 2:

### ■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB1234xxxx, is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.

16J => 1234 1 x  $32^2$  + 6 x  $32^1$  + 18 (=J) x  $32^0$  = 1234

The BASE32 code for product type B1267 is 17K.

### ■ Lot number:

The last 5 digits of the lot number, e.g., are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.

5UY => 12345

 $5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0 = 12345$ 

Adopted BASE32 code for type number						
Decimal	Base32	Decimal	Base32			
value	code	value	code			
0	0	16	G			
1	1	17	Н			
2	2	18	J			
3	3	19	K			
4	4	20	M			
5 5		21	N			
6	6	22	Р			
7	7	23	Q			
8	8 8		R			
9 9		25	S			
10	Α	26	Т			
11	В	27	V			
12	С	28	W			
13	D	29	Х			
14	E	30	Y			
15	F	31	Z			
	1	1				

Adopted BASE47 code for lot number					
Decimal	Base47	Decimal	Base47		
value	code	value	code		
0	0	24	R		
1	1	25	S		
2	2	26	Т		
3	3	27	C		
4	4	28	V		
5	5	29	W		
6	6	30	Х		
7	7	31	Υ		
8	8	32	Z		
9 9		33	b		
10	Α	34	d		
11	В	35	f		
12			h		
13 D		37	n		
14 E		38	r		
15	F	39	t		
16	G	40	V		
17	Н	41	\		
18	J	42	?		
19	K	43	{		
20	L	44	}		
21	М	45	<		
22	N	46	>		
23	Р				

Table 2: Lists for encoding and decoding of marking.

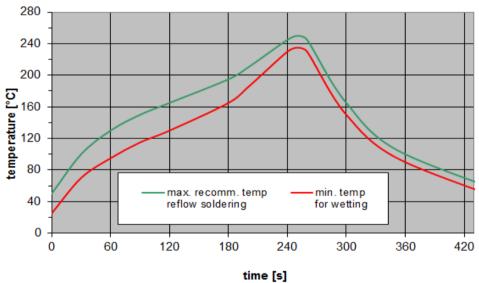


### 15 Soldering profile

The recommended soldering process is in accordance with IEC  $60068-2-58-3^{rd}$  edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	-
peak temperature $T_{\text{peak}}$	250 °C +0/-5 °C
wetting temperature $T_{min}$	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

**Table 3:** Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).



**Figure 16:** Recommended reflow profile for convection and infrared soldering – lead-free solder.



### 16 Annotations

### 16.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

### 16.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

### 16.3 Ordering codes and packing units

Ordering code	Packing unit
B39162B1267L210	15,000 pcs
B39162B1267L210S 5	5,000 pcs

Table 4: Ordering codes and packing units.



### 17 Cautions and warnings

### 17.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <a href="https://rffe.gualcomm.com/">https://rffe.gualcomm.com/</a>.

### 17.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

### 17.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

### 17.4 Package information

### Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

### **Dimensions**

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

### **Projection method**

Unless otherwise specified first-angle projection is applied.



### 18 Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
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- 3. The warnings, cautions and product-specific notes must be observed.
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